

T-1 3/4 (5mm) BLINKING LED LAMP



Part Number: L-56BQBDL-D

Blue

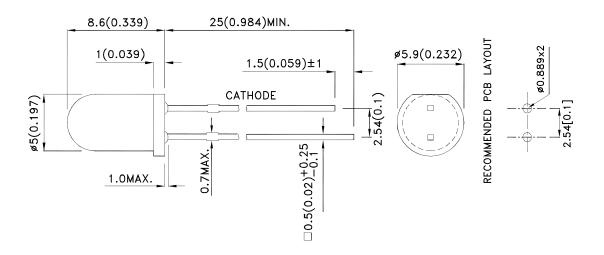
Features

- T-1 3/4 package.
- With built-in blinking IC.
- Operation voltage from 3.5V to 14V.
- Blinking frequency from 3.0Hz to 1.5Hz.
- RoHS compliant.

Descriptions

- The Blue source color devices are made with InGaN Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
 2. Tolerance is ±0.25(0.01") unless otherwise noted.
 3. Lead spacing is measured where the leads emerge from the package.
 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

DATE: NOV/18/2014 SPEC NO: DSAK1379 **REV NO: V.4B** PAGE: 1 OF 6 **APPROVED: WYNEC CHECKED: Allen Liu** DRAWN: P.Cheng ERP: 1101027388



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) V= 9V		Viewing Angle [1]
		,	Min.	Тур.	201/2
L-56BQBDL-D	Blue (InGaN)	Blue Diffused	200	350	60°

Notes

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Min.	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue		460		nm	
λD	Dominant Wavelength	Blue		465		nm	
Δλ1/2	Spectral Line Half-width	Blue		25		nm	
lF	Forward Current	Blue	4	15		mA	Min:VF=3.5V Typ:VF=5V
Ison	Supply Current	Blue		4		mA	VF=3.5V
Ison	Supply Current	Blue		41		mA	VF=14V
f	Blink Frequency	Blue	1.5		3	Hz	VF=3.5V~14V

Notes:

- 1. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

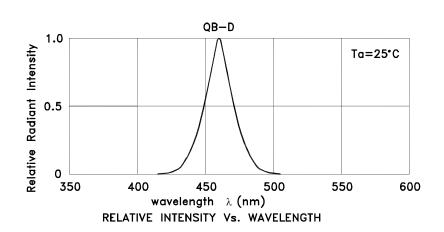
Parameter	Blue	Units		
Power dissipation	310	mW		
Forward Voltage	14	V		
Reverse Voltage	0.5	V		
Operating Temperature	-40°C To +70°C			
Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [1]	260°C For 3 Seconds			
Lead Solder Temperature [2]	260°C For 5 Seconds			

Notes

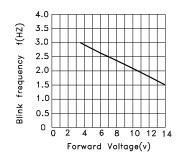
- 1. 2mm below package base.
- 2. 5mm below package base.

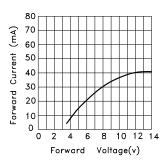
 SPEC NO: DSAK1379
 REV NO: V.4B
 DATE: NOV/18/2014
 PAGE: 2 OF 6

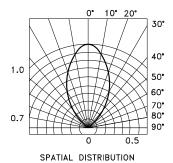
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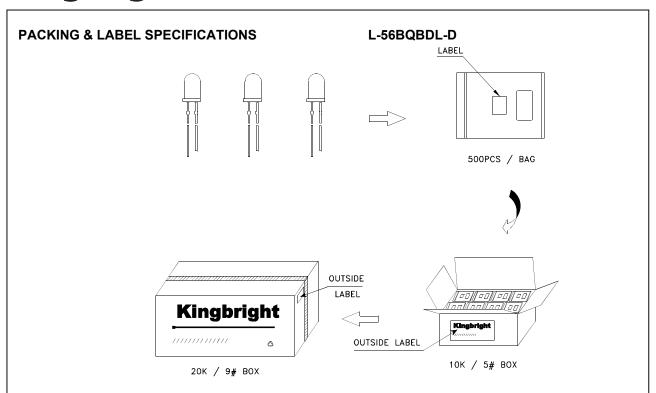
Blue L-56BQBDL-D

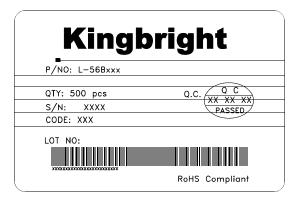






SPEC NO: DSAK1379 REV NO: V.4B DATE: NOV/18/2014 PAGE: 3 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: P.Cheng ERP: 1101027388





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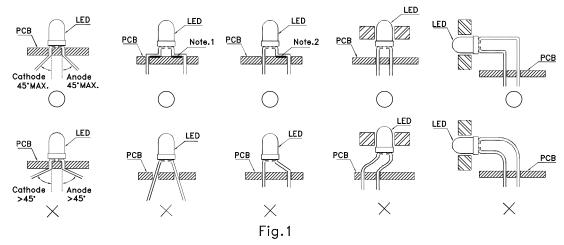
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 SPEC NO: DSAK1379
 REV NO: V.4B
 DATE: NOV/18/2014
 PAGE: 4 OF 6

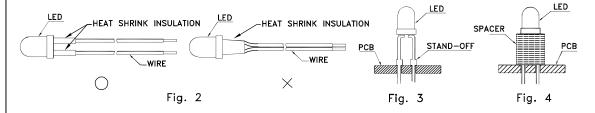
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PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



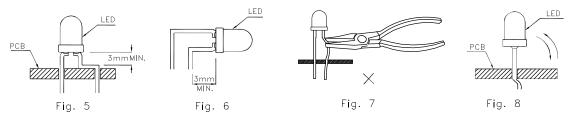
- " \bigcirc " Correct mounting method "imes" Incorrect mounting method
- 2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig.2)
- 3. Use stand—offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



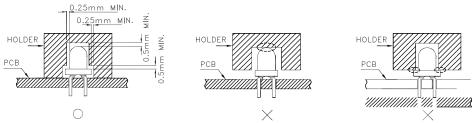
- 4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

SPEC NO: DSAK1379 APPROVED: WYNEC REV NO: V.4B CHECKED: Allen Liu DATE: NOV/18/2014 DRAWN: P.Cheng PAGE: 5 OF 6 ERP: 1101027388

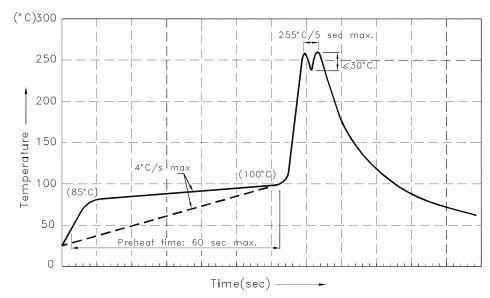
6. Do not bend the leads more than twice. (Fig. 8)



7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 8. The tip of the soldering iron should never touch the lens epoxy.
- 9. Through—hole LEDs are incompatible with reflow soldering.
- 10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 11. Recommended Wave Soldering Profiles:



Notes:

- 1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between $245^{\circ}\text{C} \sim 255^{\circ}\text{C}$ for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process. 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

SPEC NO: DSAK1379 REV NO: V.4B DATE: NOV/18/2014 PAGE: 6 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: P.Cheng ERP: 1101027388